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APPLICATION NO. FILING DATE		FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/624,766 07.		07/22/2003	Warren M. Farnworth	2741.6US (95-0804.06/US)	6771	
24247	7590	09/09/2004		EXAMINER		
TRASK E P.O. BOX			MAGEE, THOMAS J			
		UT 84110		ART UNIT	PAPER NUMBER	
				2811		
			DATE MAIL ED: 00/00/2004			

Please find below and/or attached an Office communication concerning this application or proceeding.

-	.3	Application	n No.	Applicant(s)				
•		10/624,76	6	FARNWORTH ET	AL.			
	Office Action Summary	Examiner		Art Unit				
		Thomas J.	*	2811				
Period for	The MAILING DATE of this communica	tion appears on the	cover sheet with the d	orrespondence ad	dress			
A SH THE - Exte after - If the - If NG - Faili Any	IORTENED STATUTORY PERIOD FOR MAILING DATE OF THIS COMMUNICA ensions of time may be available under the provisions of 3 of SIX (6) MONTHS from the mailing date of this communical period for reply specified above is less than thirty (30) of period for reply is specified above, the maximum statute ure to reply within the set or extended period for reply will, reply received by the Office later than three months after led patent term adjustment. See 37 CFR 1.704(b).	ATION.  7 CFR 1.136(a). In no eve cation.  ays, a reply within the statu pry period will apply and will, by statute, cause the appli	nt, however, may a reply be tir tory minimum of thirty (30) day I expire SIX (6) MONTHS from ication to become ABANDONE	nely filed /s will be considered timely the mailing date of this co ED (35 U.S.C. § 133).	<i>y.</i> ommunication.			
Status								
1)[	Responsive to communication(s) filed of	on						
2a)□	This action is <b>FINAL</b> . 2b)		on-final.					
3)	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.							
Disposit	ion of Claims							
5)□ 6)⊠ 7)□ 8)□ <b>Applicat</b> 9)□	Claim(s) 1-3 is/are pending in the appli 4a) Of the above claim(s) is/are value of Claim(s) is/are allowed.  Claim(s) 1-3 is/are rejected.  Claim(s) is/are objected to.  Claim(s) are subject to restriction is objected to by the End of Chaim(s) is/are: a	withdrawn from corn and/or election research.  Examiner.  ) accepted or b)	equirement.  objected to by the					
11)	Applicant may not request that any objection Replacement drawing sheet(s) including the The oath or declaration is objected to be	e correction is require	ed if the drawing(s) is ob	pjected to. See 37 CF				
Priority	under 35 U.S.C. § 119							
<ul> <li>12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).</li> <li>a) All b) Some * c) None of:</li> <li>1. Certified copies of the priority documents have been received.</li> <li>2. Certified copies of the priority documents have been received in Application No</li> <li>3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).</li> <li>* See the attached detailed Office action for a list of the certified copies not received.</li> </ul>								
2) Noti 3) Info	nt(s) ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO rmation Disclosure Statement(s) (PTO-1449 or PT er No(s)/Mail Date <u>07222003</u> .		4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal I 6) Other:	oate	D-152)			

## **DETAILED ACTION**

## Double Patenting

1. The nonstatutory double patenting rejection is based on a judicially created doctrine grounded in public policy (a policy reflected in the statute) so as to prevent the unjustified or improper timewise extension of the "right to exclude" granted by a patent and to prevent possible harassment by multiple assignees. See *In re Goodman*, 11 F.3d 1046, 29 USPQ2d 2010 (Fed. Cir. 1993); *In re Longi*, 759 F.2d 887, 225 USPQ 645 (Fed. Cir. 1985); *In re Van Ornum*, 686 F.2d 937, 214 USPQ 761 (CCPA 1982); *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970); and, *In re Thorington*, 418 F.2d 528, 163 USPQ 644 (CCPA 1969).

A timely filed terminal disclaimer in compliance with 37 CFR 1.321(c) may be used to overcome an actual or provisional rejection based on a nonstatutory double patenting ground provided the conflicting application or patent is shown to be commonly owned with this application. See 37 CFR 1.130(b).

Effective January 1, 1994, a registered attorney or agent of record may sign a terminal disclaimer. A terminal disclaimer signed by the assignee must fully comply with 37 CFR 3.73(b).

2. Claims 1 – 3 are rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over Claim 1 of US Patent No. 6,597,066 B1 in view of Rostoker et al., U.S. Patent No. 5,453,583. Although the conflicting claims are not identical, the claimed subject matter of the patent and the instant application are not patentably distinct from each other because of the following reasons:

The claimed subject matter of the instant application, i.e., "a semiconductor wafer having a plurality of semiconductor devices formed thereon, comprising ...... a plurality of metal circuits being connected to the at least one bond pad of each of the at least two semiconductor devices, the at least one metal circuit sealingly engaging the first coating on the portion of a semiconductor wafer substrate and the at least one bond pad of each of the at least two semiconductor devices," is already claimed in Claim 1 of U.S. Patent No. 6,597,066 B1.

Claim 1 of Patent No. 6,597,066 B1 discloses the claimed structure except for the limitation of a "plurality of metal circuits formed thereon." However, since a semiconductor wafer contains a large number of semiconductor devices with a large number of leads (metal circuits) connected to bond pads, it would be obvious that "at least one metal circuit" is connected to at least one bond pad on the wafer portion.

Additionally, this is also disclosed by Rostoker et al. (Figure 4) wherein leads (435a,435b) are connected to bond pads (420a,420b) of die, 410, and multiple devices are contained on the wafer.

Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to incorporate the multiple leads of Rostoker et al. in Patent No. 6,597,066 B1 to form a plurality of metal circuits connected to bond pads.

Furthermore, the claimed inventions of Claims 2 and 3 are within the scope of the claimed limitations of U.S. Patent No. 6,597,066 B1.

## **Conclusions**

Any inquiry concerning this communication or earlier communications from the Examiner should be directed to **Thomas Magee**, whose telephone number is **(571) 272 1658.** The Examiner can normally be reached on Monday through Friday from 8:30AM to 5:00PM (EST). If attempts to reach the Examiner by telephone are unsuccessful, the examiner's supervisor, **Eddie Lee**, can be reached on **(571) 272-1732.** The fax number for the organization where this application or proceeding is assigned is **(703)** 

Application/Control Number: 10/624,766

Art Unit: 2811

872-9306.

Thomas Magee August 30, 2004

EDDIE LEE

SUPERVISORY PATENT EXAMINER TECHNOLOGY CENTER 2800